

ABSTRACT OF THE DISCLOSURE

**RESIN COMPOSITION, ADHESIVE FILM FOR SEMICONDUCTOR DEVICE,
AND LAMINATED FILM WITH METALLIC FOIL AND SEMICONDUCTOR
DEVICE USING THE SAME**

A resin composition has a phase separation structure having at least two phases and inorganic particles having a mean primary particle size of 0.1 μm or less. The phase separation structure includes a matrix phase and a disperse phase. The inorganic particles are mainly present in any one of the matrix phase, the disperse phase, and the interface between the matrix phase and the disperse phase. The resin composition has a high thermal expansion coefficient and elastic modulus, and thus provides an adhesive for semiconductor devices which has excellent reflow resistance and adhesion.

(FIG. 1)



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